To: Commissioner of Patents and Trademarks Washington; D.C. 20231

Fr: George O. Saile

Reg. No. 19,572

28 Davis Avenue

Poughkeepsie, N.Y. 12603

Subject:

**Divisional Patent Application** of

Serial No.: 10/205,520 7/25/02

YI-HSU WU,JIAN-HSING LEE,SHUI-HUNG CHEN

WHOLE CHIP ESD PROTECTION

## PRELIMINARY AMENDMENT

Dear Sir:

This is a preliminary amendment for the above referenced Divisional Patent

Application. Please amend the above identified application for patent as follows:

## **CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on April 8, 2004.

Stephen B. Ackerman, Reg. No. 37,761

Signature/Date

4/8/04